

In re Appln. of Wang et al.  
Application No. 09/636,161

IN THE CLAIMS:

Please add the following new claims.

32. (New) The system of claim 1, wherein at least one polishing additive is iminodiacetic acid.

33. (New) The system of claim 32, wherein the system further comprises at least one stopping compound.

34. (New) The system of claim 32, wherein the system further comprises at least one polymeric compound that reduces the polishing rate of at least one layer associated with the substrate.

35. (New) The system of claim 22, wherein the system further comprises ammonia or an ammonium salt.

36. (New) A method of polishing one or more layers of a multi-layer substrate that includes a first noble metal layer and a second layer comprising:

- (i) contacting the substrate with a chemical-mechanical polishing system comprising:
  - (a) a liquid carrier,
  - (b) at least one oxidizing agent,
  - (c) at least one polishing additive that increases the rate at which the system polishes the noble metal layer of the substrate, wherein the polishing additive is selected from the group consisting of carboxylates and acids thereof, hydroxylates and acids thereof, carbonylates and acids thereof, pyrophosphates, condensed phosphates, phosphonic acids and salts thereof, amines, amino alcohols, amides, imines, imino acids and salts thereof, nitriles, nitros, thiols, thioesters, thioethers, carbothiolic acids and salts thereof, carbothionic acids and salts thereof, thiocarboxylic acids and salts thereof, sulfonic acids and salts thereof, thiosalicylic acids and salts thereof, and mixtures thereof, and
  - (d) a polishing pad and/or an abrasive, and
- (ii) abrading at least a portion of the substrate to polish the substrate.

37. (New) The method of claim 36, wherein the oxidizing agent is a per-compound.